



CER1125A - PRELIMINARY 3.76-3.80GHz BPF

Features

- Low Loss with High Rejection
- Similar to UMB family, but not footprint-compatible

Applications

 High-performance carrier-grade wireless infrastructure applications



Materials: Ag plated ceramic block with tin plated brass shield

Description

Surface mount ceramic bandpass filter with superior rejection, insertion loss, reliability, as well as both peak and average power handling compared to other bandpass filter technologies.

Electrical Specifications (These specs are NOT guaranteed. Will be revised following prototype run.)

Frequency (MHz)	Typical at 25°C	Spec. at 25°C	Spec. over -40°C to +105°C
-	50 ohms	-	-
-	-	-	10.0 Watt max
-	-	-	100 Watt max
3760-3800	2.1 dB	2.2-2.4 dB max	2.2-2.4 dB max
3760-3800	1.5 dB	1.7-1.8 dB max	1.7-1.8 dB max
3760-3800	1.0 dB	1.1-1.3 dB max	1.1-1.3 dB max
3760-3800	15 dB	13 dB min	13 dB min
1-2700	50 dB	40 dB min	40 dB min
2701-3660	40 dB	30 dB min	30 dB min
3661-3740	24 dB	20 dB min	20 dB min
3820 -3899	24 dB	20 dB min	20 dB min
3900-4900	40 dB	30 dB min	30 dB min
	(MHz) 3760-3800 3760-3800 3760-3800 3760-3800 1-2700 2701-3660 3661-3740 3820-3899	(MHz) at 25°C - 50 ohms 3760-3800 2.1 dB 3760-3800 1.5 dB 3760-3800 1.0 dB 3760-3800 15 dB 1-2700 50 dB 2701-3660 40 dB 3661-3740 24 dB	(MHz) at 25°C at 25°C - 50 ohms

Note: CTS tests each unit to the critical specifications above. Subsequent audits may deviate due to repeatability among different test systems which shall not exceed these allowances.

Specification Allowance
Insertion Loss 0.1 dB
Return Loss 1.0 dB
Attenuation 1.0 dB

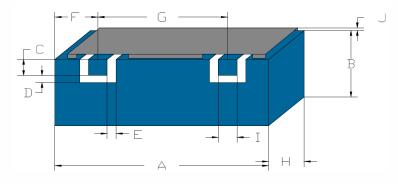
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Mechanical Drawing



PCB Layout			
Filter Outline Solder Resist Over Dielectric Exposed Conductor Solder Resist Over Conductor			

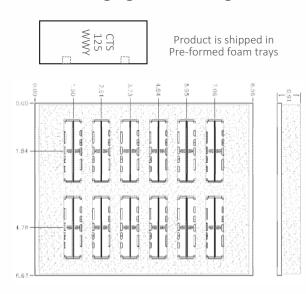
Dim.	Nominal (mm)	Tolerance
Α	57.00	max
В	3.70	max
С	1.00	0.13
D	0.50	0.13
Е	0.50	0.13
F	n/a	0.25
G	37.0	0.13
Н	15.00	max
I	1.00	0.13
J	2.50	max

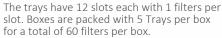
IMPORTANT: Please assure >=30mils (0.75mm) thickness of dielectric beneath the I/O Pads and the surrounding clearance zone down to the required ground plane.

Please assure sufficient ground vias between the top metal ground plane and the primary ground plane.

Recommended solder: 6 mils of SAC305 with reflow including 120s of soak at 217°C, and up to 30 sec peak at 241°C.

Packaging and Marking





Electrical Response

